

ABSTRACT

A lead frame and a semiconductor package with the lead frame are provided. The lead frame includes a die pad for mounting at least one semiconductor chip thereon; at least one grounding portion protruded from the die pad; and a plurality of leads. The grounding portion has a grounding surface and an opposing bottom surface, wherein the thickness of the grounding portion is smaller than that of the die pad, and a ground pad is formed on the grounding surface for connecting at least one grounding wire to the chip for transmitting ground signals. A plurality of bonding wires are connected from the chip to the leads such that the chip can be electrically connected to an external device via the bonding wires and leads. By the above arrangement, the grounding wire can be prevented from breakage by thermal stress in a high-temperature process, and the production yield is improved.

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